



PRODUCT BULLETIN
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28 Feb 2008

SUBJECT: ON Semiconductor Product Bulletin # 16104

TITLE: 40 pin QFN 6x6 mm body size package Moisture Sensitivity Level (MSL) upgrade

PROPOSED FIRST SHIP DATE: 28 Feb 2008

AFFECTED PRODUCT DIVISION: Analog Power Switching Business Unit of the Computing Products Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or Rob Swanson <Rob.Swanson@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact your local ON Semiconductor sales office.

DESCRIPTION AND PURPOSE:

Due to ongoing process improvements, ON Semiconductor is pleased to announce the Moisture Sensitivity Level (MSL) rating of the 40 pin QFN 6x6 mm body size package from assembly subcontractor UTAC (formerly known as NSEB) in Bangkok, Thailand, has been upgraded from MSL-3 at the 260°C solder reflow temperature (Pb-Free profile) up to MSL-1 at 260°C, per J-STD-020 Revision C requirements. Thus, dry packing is no longer required for shipments, effective immediately.

Data is available upon request.

AFFECTED DEVICE LIST

NCP5387MNR2G
NCP5398MNR2G